

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Sean Michael Malolepszy, et al.** Docket No.: **TI-33434.1**  
Serial No.: **TBD** Examiner: **TBD**  
Filed: **Herewith** Art Unit.: **TBD**  
For: **Bond Surface Conditioning System For** Conf. No.: **TBD**  
**Improved Bondability**

**TRANSMITTAL OF FORMAL DRAWINGS**

Commissioner For Patents  
Attn: Official Drafts Person  
Alexandria, VA 22313-1450

<b>MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)</b>	
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner For Patents, Alexandria, VA 22313-1450.	
 Elizabeth Austin	7/1/2003 Date

Dear Sir:

Submitted herewith are 5 sheets of formal drawings.

The enclosed drawings are being provided in a timely manner therefore no additional fee is required.

Respectfully submitted,



Michael K. Skrehot  
Attorney for Applicants  
Reg. No.: 36,682

Texas Instruments Incorporated  
P. O. Box 655474, MS 3999  
Dallas, Texas 75265  
(972) 917-5653